Notification# 20151215004
Datasheet for TMP275
Information Only

Date: 12/16/2015
To: TOKYO ELECTRON DEVICE (DSTR) PCN

Dear Customer:

This is an information-only announcement of a change to a device that is currently offered by Texas Instruments.

The changes discussed within this notification are for your information only.

Any negotiated alternative change requirements will be provided via the customer's defined process. Customers with previously negotiated, special requirements will be handled separately. Any inquiries should be directed to your local Field Sales Representative.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Manager (PCN_ww_admin_team@list.ti.com).

Sincerely,

PCN Team
SC Business Services

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
TMP275AIDGKR	null
TMP275AIDGKT	null

Technical details of this Product Change follow on the next page(s).

PCN Number:	20151215004			PCN Date:	12/16/2015
Title:	Datasheet for TMP275				
Customer Contact:	PCN Manager			Dept:	Quality Services

Change Type:

☐	Assembly Site	☐	Design	☐	Wafer Bump Site
☐	Assembly Process	☒	Data Sheet	☐	Wafer Bump Material
☐	Assembly Materials	☐	Part number change	☐	Wafer Bump Process
☐	Mechanical Specification	☐	Test Site	☐	Wafer Fab Site
☐	Packing/Shipping/Labeling	☐	Test Process	☐	Wafer Fab Materials
				☐	Wafer Fab Process

Notification Details

Description of Change:

Texas Instruments Incorporated is announcing an information only notification etc.

The product datasheet(s) is being updated as summarized below.

The following change history provides further details.

TEXAS INSTRUMENTS

TMP275

SBOS363E – JUNE 2006 – REVISED NOVEMBER 2015

Changes from Revision D (August 2007) to Revision E   Page

- Added *Handling Rating* table, *Feature Description* section, *Device Functional* Modes, *Application and Implementation* section, *Power Supply Recommendations* section, *Layout* section, *Device and Documentation Support* section, and *Mechanical, Packaging, and Orderable Information* section 1
- Changed the Timing Requirements table with new I^{2}C data. Updated affected values throughout the data sheet 6

Device Family	Change From:	Change To:
TMP275	SBOS363D	**SBOS363E**

These changes may be reviewed at the datasheet links provided.
http://www.ti.com/product/TMP275

Reason for Change:

To more accurately reflect device characteristics.

Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):

No anticipated impact. This is a specification change announcement only. There are no changes to the actual device.

Changes to product identification resulting from this PCN:

None.

Product Affected:

TMP275AID	TMP275AIDG4	TMP275AIDGKR	TMP275AIDGKRG4
TMP275AIDGKT	TMP275AIDGKTG4	TMP275AIDR	TMP275AIDRG4

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com